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Performance results are based on testing as of dates shown in configurations and may not reflect all publicly available updates. See backup for configuration details. No product or component can be absolutely secure.

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Hot Chips 2023

#### Hot Chips 2023

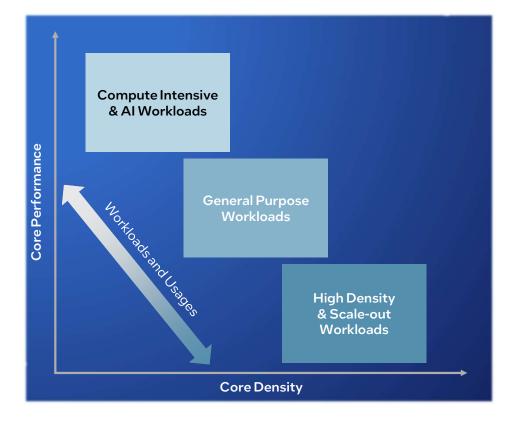
# The Next Generation of High Performance, Energy-Efficient Computing: Intel® Xeon® Processors Built on Efficient-Core

Don Soltis Senior Principal Engineer, Xeon with Efficient-Core Architect, Intel

Stephen Robinson Intel Fellow, Efficiency Core Architect



## **Data Center Requirements Are Expanding**



Continuing demand to increase core performance, power efficiency and throughput performance

Deliver the best performance per Watt at the desired core performance

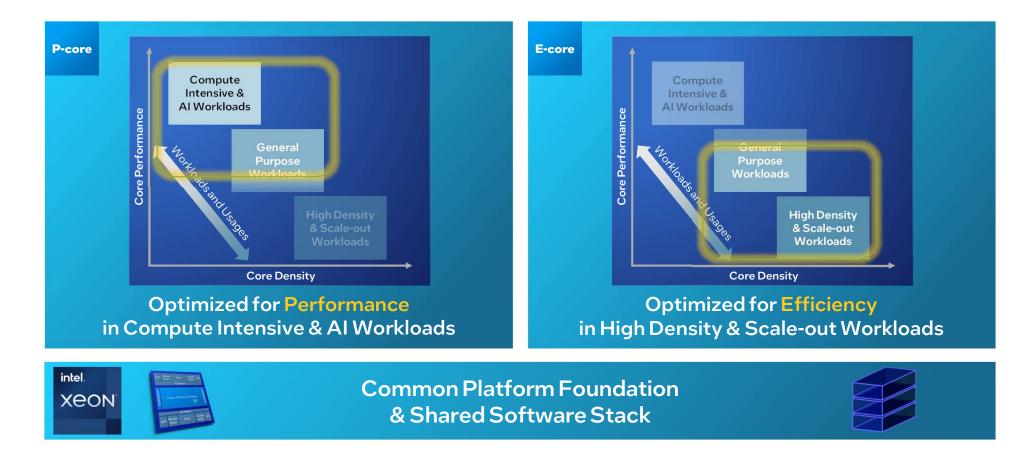
Workload requirements place trade-offs between core performance & core density

Expanding deployment models demanding increased power, IO & memory bandwidth

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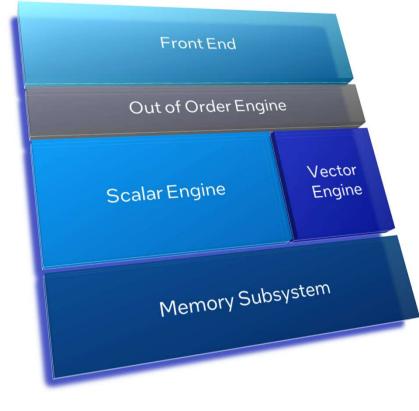
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## **Expanded Xeon Product Portfolio with Optimized Processors**



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# Intel's Newest Data Center Efficiency Optimized E-Core Microarchitecture



Designed for scalable throughput performance

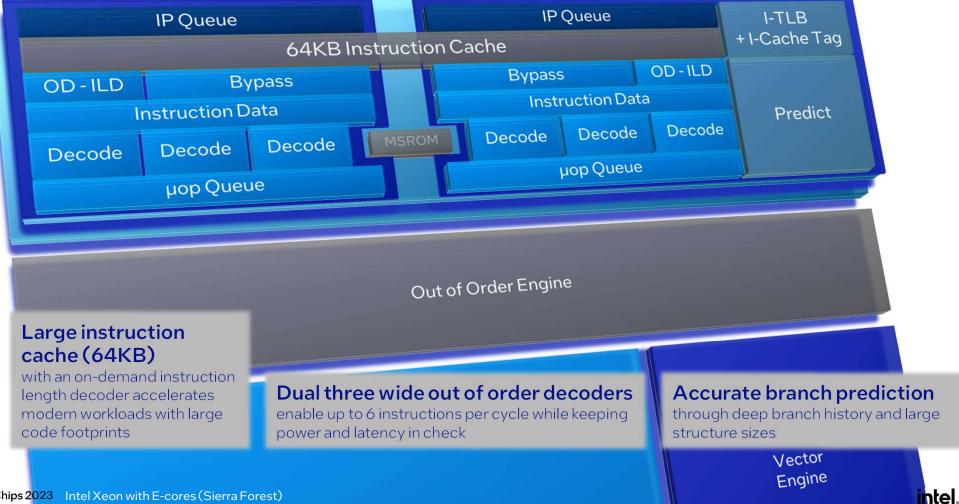
Optimized for power and density efficient throughput with:



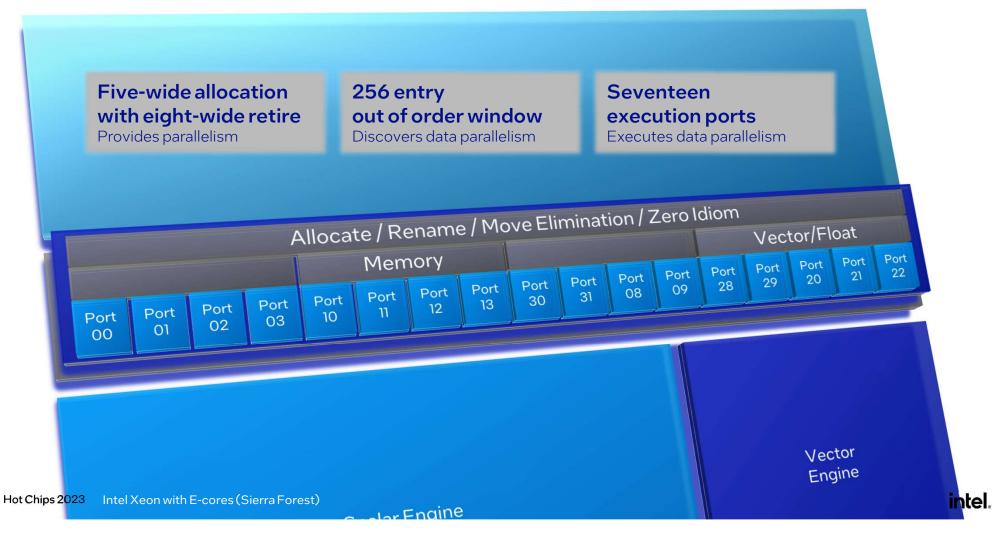
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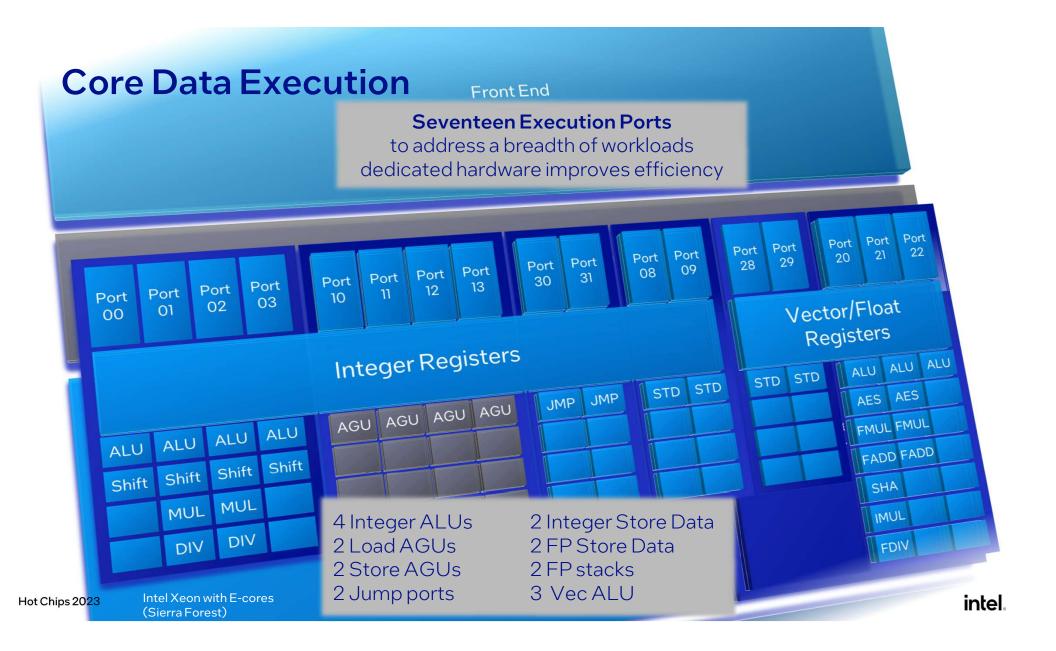
## **Core Instruction Control**

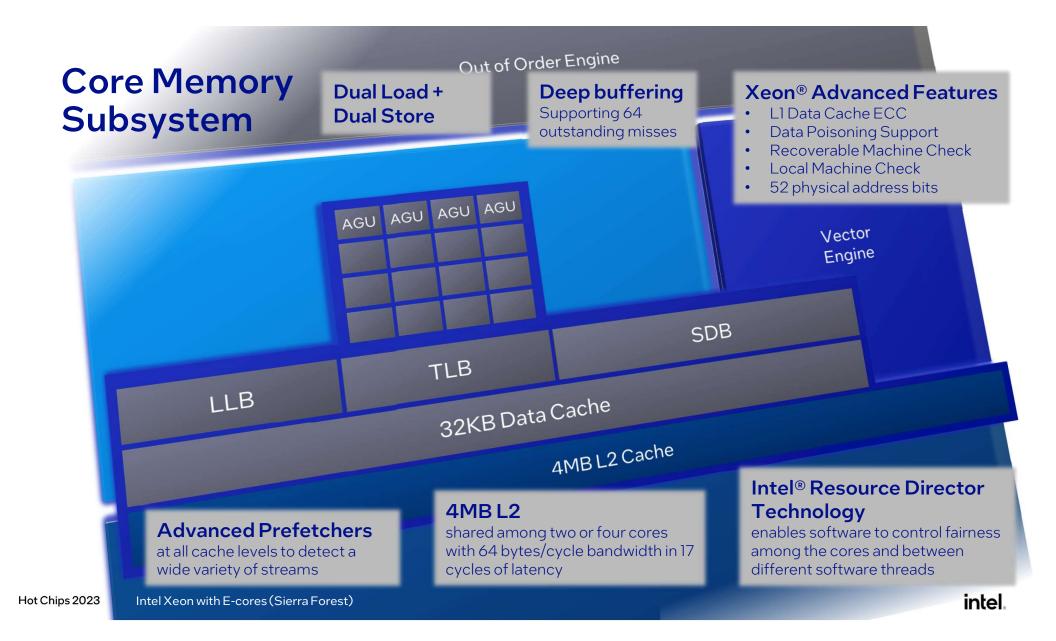


## **Core Execution**



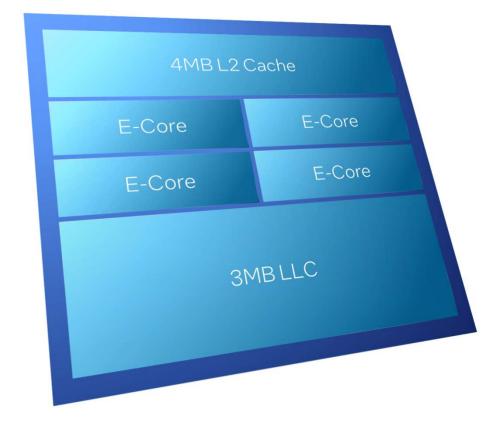
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Modern Instruction Set	Vector	
Security Features	Support for Advanced Vector Instructions with AI extensions	ALU ALU ALU AES AES
Intel <sup>®</sup> Control-Flow Enforcement Technology (Intel <sup>®</sup> CET) designed to improve defense in depth	Wide Vector Instruction Set Architecture	FMUL FMUL FADD FADD
<b>Intel® VT-rp</b> (Virtualization Technology redirect protection) Supported	Floating point multiply- accumulate (FMA) instructions for 2x throughput	SHA
Advanced speculative execution validation methodology	Key instruction additions to enable integer AI throughput	FDIV
Hot Chips 2023 Intel Xeon with E-cores (Sierra Forest) intel.		

## **Core Tile**



#### **2 or 4 cores per module** Shared L2 cache Shared frequency and voltage domain Shared mesh fabric interface

#### **Each core is single threaded** Providing performance isolation

**LLC slice shared among all cores in socket** High bandwidth pipeline per slice

## **Package View**

## I/O Chiplet

Common with Xeon P-core (Granite Rapids) PCIe gen 5, CXL 2.0, UPI coherency links Crypto, compression, data streaming accelerators Self-boot

## **Compute Chiplet**

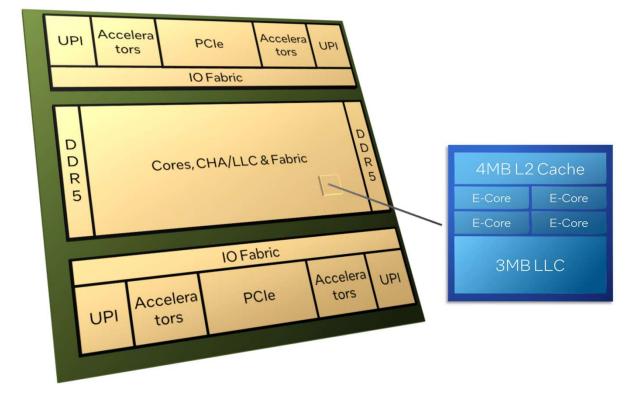
Mesh of core tiles Single domain, shared Last-Level cache DDR5 6400 interface

## Security Isolation<sup>1</sup>

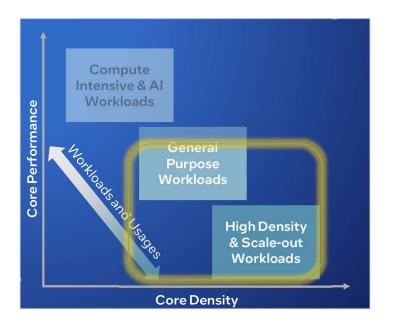
Intel<sup>®</sup> Trusted Domain Extensions (Intel TDX) Intel<sup>®</sup> Software Guard Extensions (Intel SGX)

## Focus on Throughput Performance

Up to 288 cores (2S) 205W and higher power per socket



# Harness the Efficiency of Xeon with E-cores



Improve OpEx and CapEx Increased performance per Watt at increased core density

Augments Xeon breadth of coverage Same hardware, software and firmware

Vector and Al Instruction Support Including support for FP16, BF16 and INT8 data types

**Focus on throughput, density and efficiency** Optimize across full range of utilization

intel Xeon

Highly Scalable Architecture To Address the Throughput Efficiency Needs For the Next Decade of Compute

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Intel Xeon with E-cores (Sierra Forest)

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# Thank You

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# References

TDX <u>https://www.intel.com/content/www/us/en/developer/articles/technical/intel-trust-domain-extensions.html</u>

VT-rp<u>https://www.intel.com/content/dam/www/central-libraries/us/en/documents/intel-virtualization-technologies-white-paper.pdf</u>

CET <u>https://www.intel.com/content/www/us/en/developer/articles/technical/technical-look-control-flow-enforcement-technology.html</u>

VNNI <u>https://community.intel.com/t5/Blogs/Tech-Innovation/Artificial-Intelligence-AI/Deep-Learning-Performance-Boost-by-Intel-VNNI/post/1335670</u>

CXL <a href="https://www.computeexpresslink.org/">https://www.computeexpresslink.org/</a>

## New instruction set extensions

https://www.intel.com/content/www/us/en/developer/articles/technical/intel-sdm.html#inpage-nav-4

